

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10552540			
<b>Filing Date:</b>	11-Oct-2005			
<b>Title of Invention:</b>	THERMOSETTING RESIN COMPOSITION, MULTILAYER BODY USING SAME, AND CIRCUIT BOARD			
<b>First Named Inventor/Applicant Name:</b>	Shigeru Tanaka			
<b>Filer:</b>	Dariusz G. Adli/Reynaldo Gallardo			
<b>Attorney Docket Number:</b>	81844.0044			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	4	3	12
<b>Total in USD (\$)</b>				<b>1822</b>